# Product Preview

# VDP Multiple Pixel Clock Generator

# **Product Description**

The PCS1P2192A is a clock generator that generates multiple selectable pixel clock outputs for Video Display Panel applications from an external 20 MHz reference clock. The PLL based clock generator is specifically designed to provide zero ppm frequency synthesis error on all clock outputs. Various pixel clock rates are selectable through frequency selection pins S[2:0] (Refer to Frequency Selection Table) The device provides a reference clock output additionally. Operating Supply Voltage for this device is 3.3 V  $\pm 0.3$  V. The device is available in an 8-pin SOIC package.

## **Application**

PCS1P2192A is targeted towards Video Display Panel (VDP) applications like VGA, SVGA, XGA, WXGA, UXGA.

#### **Features**

- Generates Multiple Clock Outputs from 20 MHz External Reference Clock
- Input Frequency: 20 MHz
- Output Frequencies:
  - Selectable CLKOUT:
     108 MHz, 27 MHz, 33.2 MHz, 85 MHz, 65 MHz, 25 MHz,
     45 MHz, and 40 MHz
  - ◆ REFOUT: 20 MHz
- Operating Supply Voltage:  $3.3 \text{ V} \pm 0.3 \text{ V}$
- Zero ppm Frequency Synthesis Error on all Clock Outputs
- 8-pin SOIC Package
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

This document contains information on a product under development. ON Semiconductor reserves the right to change or discontinue this product without notice.



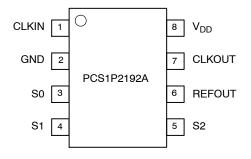
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SOIC8-NB EP CASE 751BU

#### PIN CONFIGURATION



#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

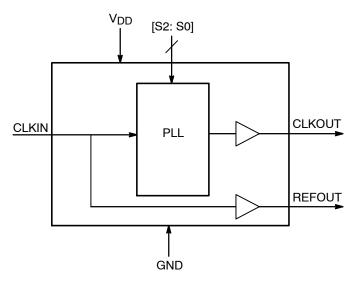


Figure 1. Block Diagram

**Table 1. PIN DESCRIPTION** 

Pin #	Pin Name	Туре	Description
1	CLKIN	Input	20 MHz external reference clock input.
2	GND	Power	Ground Connection.
3	S0	Input	Frequency select. Digital logic input used to select output frequency. Has an internal pull up resistor. (Refer to <i>Frequency Selection Table</i> .)
4	S1	Input	Frequency select. Digital logic input used to select output frequency. Has an internal pull up resistor. (Refer to <i>Frequency Selection Table</i> .)
5	S2	Input	Frequency select. Digital logic input used to select output frequency. Has an internal pull up resistor. (Refer to <i>Frequency Selection Table</i> .)
6	REFOUT	Output	Reference clock output.
7	CLKOUT	Output	Clock output.
8	$V_{DD}$	Power	Device Power Supply.

**Table 2. FREQUENCY SELECTION TABLE** 

S2	S1	S0	CLKOUT (MHz)
0	0	0	108
0	0	1	27
0	1	0	33.2
0	1	1	85
1	0	0	65
1	0	1	25
1	1	0	45
1	1	1	40

**Table 3. ABSOLUTE MAXIMUM RATINGS** 

Symbol	Parameter	Rating	Unit
$V_{DD}, V_{IN}$	Voltage on any input pin with respect to Ground	-0.5 to +4.6	V
T <sub>STG</sub>	Storage temperature	-65 to +125	°C
T <sub>s</sub>	Max. Soldering Temperature (10 sec)	260	°C
TJ	Junction Temperature	150	°C
T <sub>DV</sub>	Static Discharge Voltage (As per JEDEC STD22- A114-B)	2	KV

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

**Table 4. RECOMMENDED OPERATING CONDITIONS** 

Parameter	Description	Min	Тур	Max	Unit
V <sub>DD</sub>	Operating Voltage	3.0	3.3	3.6	V
T <sub>A</sub>	Operating Temperature	0		+85	°C
CL	Load Capacitance			15	pF
C <sub>IN</sub>	Input Capacitance			7	pF

# Table 5. DC ELECTRICAL CHARACTERISTICS

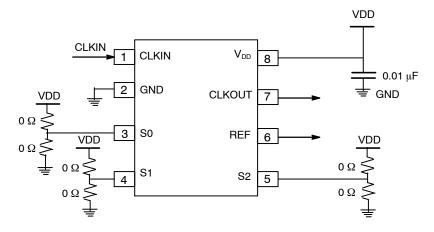
Symbol	Parameter	Min	Тур	Max	Unit
V <sub>IL</sub>	Input low voltage (for CLKIN)	GND - 0.3		0.8	V
V <sub>IH</sub>	Input high voltage (for CLKIN)	2.0		VDD + 0.3	V
I <sub>IL</sub>	Input low current			50	μΑ
I <sub>IH</sub>	Input high current			-50	μΑ
V <sub>OL</sub>	Output low voltage (VDD = 3.3 V, I <sub>OL</sub> = 8 mA)			0.4	V
V <sub>OH</sub>	Output high voltage (VDD = 3.3 V, I <sub>OH</sub> = -8 mA)	2.4			V
I <sub>DD</sub>	Static supply current (Note 1)			5	mA
I <sub>CC</sub>	Dynamic supply current (3.3 V and no load)		9		mA
$V_{DD}$	Operating Voltage	3.0	3.3	3.6	V
t <sub>ON</sub>	Power-up time (first locked cycle after power-up)		1		mS
Z <sub>OUT</sub>	Output impedance		40		Ω

<sup>1.</sup> CLKIN pulled low.

## **Table 6. AC ELECTRICAL CHARACTERISTICS**

Symbol	Parameter	Min	Тур	Max	Unit
f <sub>IN</sub>	Input frequency		20		MHz
fouт	Output frequency		108, 27, 33.2, 85, 65, 25, 45, 40		MHz
t <sub>LH</sub> (Note 2)	Output rise time (Measured from 20% to 80%)	1.2		2.5	nS
t <sub>HL</sub> (Note 2)	Output fall time (Measured from 80% to 20%)	0.8		1.6	nS
t <sub>JC</sub>	Period Jitter		±150		pS
	Frequency Synthesis Error (All Outputs)		0		ppm
t <sub>D</sub>	Output duty cycle	40	50	60	%

<sup>2.</sup> Measured with a capacitive load of 15 pF.



Use either pull–up or pull–down 0  $\Omega$  Resistor with [S2:S0] for selection of CLKOUT frequencies.

Figure 2. Typical Application Schematic

#### **PCB Layout Recommendation**

For optimum device performance, following guidelines are recommended.

- Dedicated VDD and GND planes.
- The device must be isolated from system power supply noise. A  $0.01~\mu F$  decoupling capacitor should be mounted on the component side of the board as close to the VDD pin as possible. No vias should be used between the decoupling capacitor and VDD pin. The
- PCB trace to VDD pin and the ground via should be kept as short as possible. All the VDD pins should have decoupling capacitors.
- In an optimum layout all components are on the same side of the board, minimizing vias through other signal layers.

A typical layout is shown in the Figure 3.

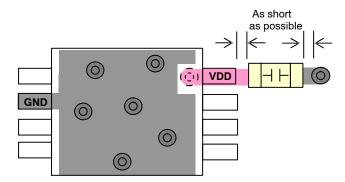
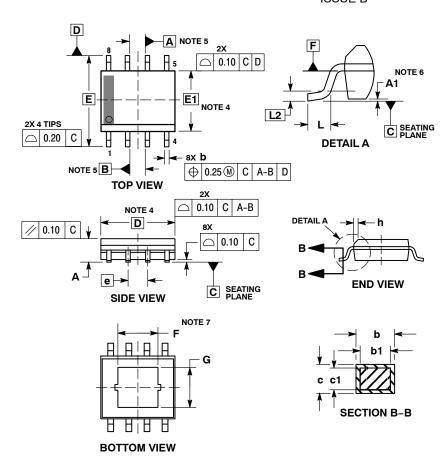


Figure 3. Typical Layout

#### PACKAGE DIMENSIONS

#### SOIC8-NB EP CASE 751BU **ISSUE B**



#### NOTES:

- DIMENSIONING AND TOLERANCING PER ASME
- Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS
- DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.10mm IN EXCESS OF MAXIMUM MATERIAL CONDITION.
- CONDITION.

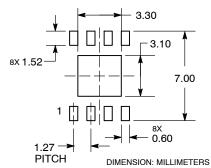
  DIMENSION D DOES NOT INCLUDE MOLD FLASH,
  PROTRUSIONS, OR GATE BURRS. MOLD FLASH,
  PROTRUSIONS, OR GATE BURRS SHALL NOT
  EXCEED 0.15mm PER SIDE. DIMENSION E DOES
  NOT INCLUDE INTERLEAD FLASH OR
  PROTRUSION. INTERLEAD FLASH OR
  PROTRUSION. SHALL NOT EXCEED 0.25mm PER
  SIDE DIMENSIONS AND EXCEED 0.25mm PER SIDE. DIMENSIONS D AND E ARE DETERMINED AT DATUM F.
  DIMENSIONS A AND B ARE TO BE DETERMINED AT DATUM F.
- A I DATUM F.

  6. A1 IS DEFINED AS THE VERTICAL DISTANCE
  FROM THE SEATING PLANE TO THE LOWEST
  POINT ON THE PACKAGE BODY.

  7. TAB CONTOUR MAY VARY MINIMALLY TO INCLUDE
- TOOLING FEATURES.

	MILLIMETERS			
DIM	MIN	MAX		
Α	1.35	1.75		
<b>A</b> 1		0.10		
b	0.31	0.51		
b1	0.28	0.48		
С	0.17	0.25		
c1	0.17	0.23		
D	4.90 BSC			
Ε	6.00 BSC			
E1	3.90	BSC		
е	1.27	7 BSC		
F	1.55	3.07		
G	1.55	3.07		
h	0.25	0.50		
L	0.40	1.27		
L2	0.25 BSC			

#### **RECOMMENDED SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### **Table 7. ORDERING INFORMATION**

Part Number	Top Marking	Package Type	Temperature
PCS1P2192AG-08SR	ACZ	8-Pin SOIC, TAPE & REEL, Green	0°C to +85°C

NOTE: A "microdot" placed at the end of last row of marking or just below the last row toward the center of package indicates Pb-free.

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